

COVER TAPE

ABSTRACT

Disclosed is a cover tape which comprises at least a base layer (A), an intermediate layer (B), a peeling layer (C), the primary component of which is a thermoplastic resin, and a heat seal layer (D), the primary component of which is a thermoplastic resin that can be heat sealed to a carrier tape. The tensile storage modulus (c) of the thermoplastic resin that constitutes the peeling layer (C) is within the range of 1×10^6 Pa to 1×10^8 Pa. The tensile storage modulus (d) of the thermoplastic resin that constitutes the heat seal layer (D) is within the range of 1×10^8 Pa to 1×10^{10} Pa. The ratio of (c) and (d) satisfies $1 \times 10^4 \geq (d)/(c) \geq 1 \times 10$. This kind of cover tape has the appropriate peel strength and sufficiently low fluctuation in peel strength when heat sealed to a thermoplastic resin carrier tape. Therefore, the tape will not tear even under shock caused by high-speed peeling, and sticking of electronic parts does not occur even when set aside for a long period of time of 24 to 72 hours in a high-temperature environment of 60 to 80 °C.

[FIG. 1]